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(12) United States Design Patent

Kawase

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(54) **SEMICONDUCTOR DEVICE**

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(73) Assignee: **Mitsubishi Electric Corporation**, Tokyo (JP)

(**) Term: **15 Years**

(21) Appl. No.: **29/591,886**

(22) Filed: **Jan. 25, 2017**

Related U.S. Application Data

(62) Division of application No. 29/555,470, filed on Feb. 22, 2016, now Pat. No. Des. 785,577, which is a (Continued)

(30) **Foreign Application Priority Data**

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(51) **LOC (10) Cl.** **13-03**

(52) **U.S. Cl.**
USPC **D13/182**

(58) **Field of Classification Search**
USPC D13/110, 182; 257/678, 684, 690, 691; 361/679.01, 713, 728, 736, 760, 761, 772, 361/775, 783, 820; 174/250, 253; 438/15, 25, 26, 51, 55, 63, 64, 106
CPC . H01L 21/00; H01L 2224/42; H01L 2224/43; H01L 2021/00; H01L 2021/02; H01L 2021/04; H01L 21/4814; H01L 21/4846; H01L 21/4871; H01L 21/67144; H01L 23/12; H01L 23/13; H01L 23/14; H01L 23/147; H01L 2924/171; H01L 2924/1711; H01L 2924/1715; H01L 2924/171151; H01L 2924/181; H01L
(Continued)

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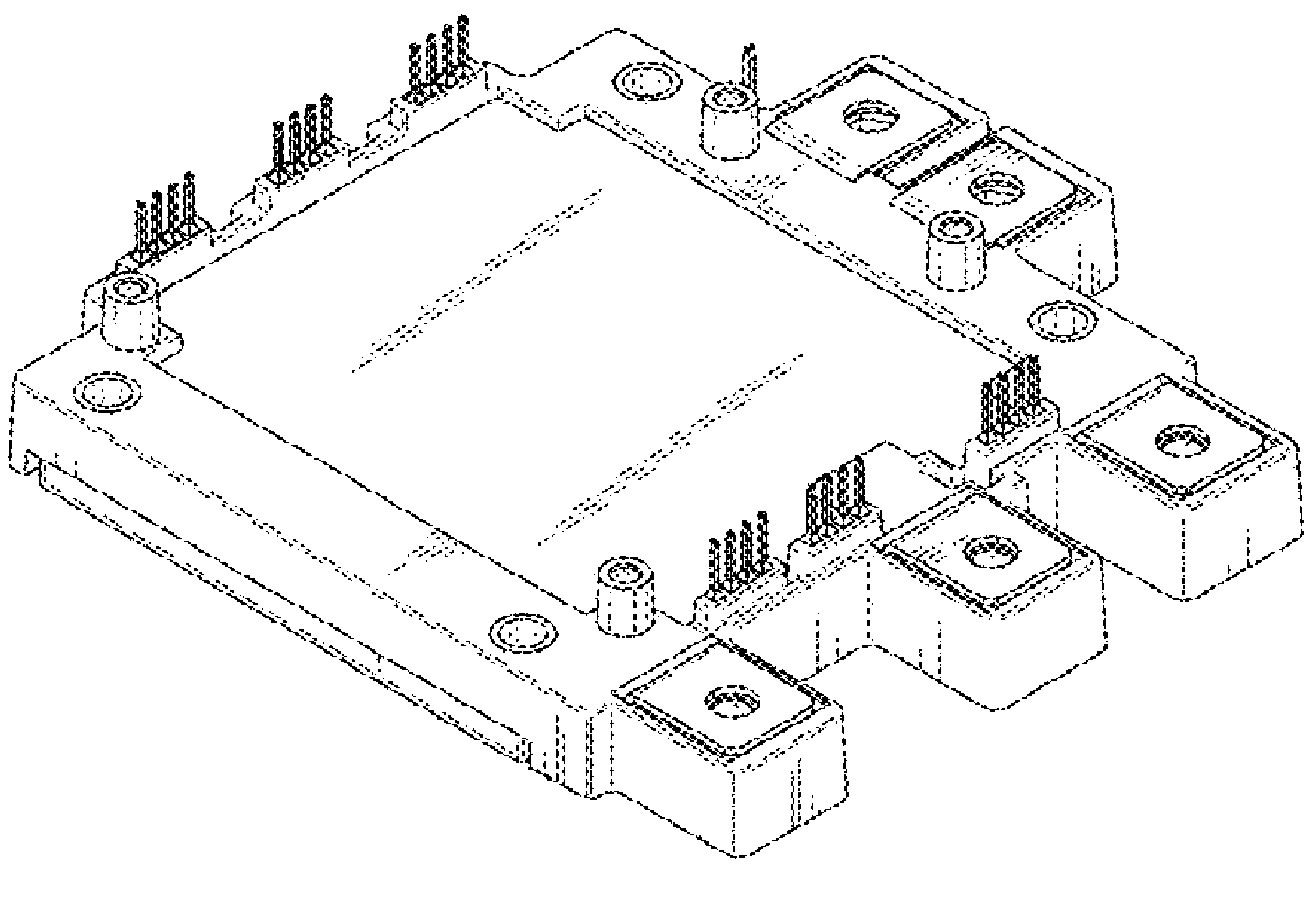
(57) **CLAIM**

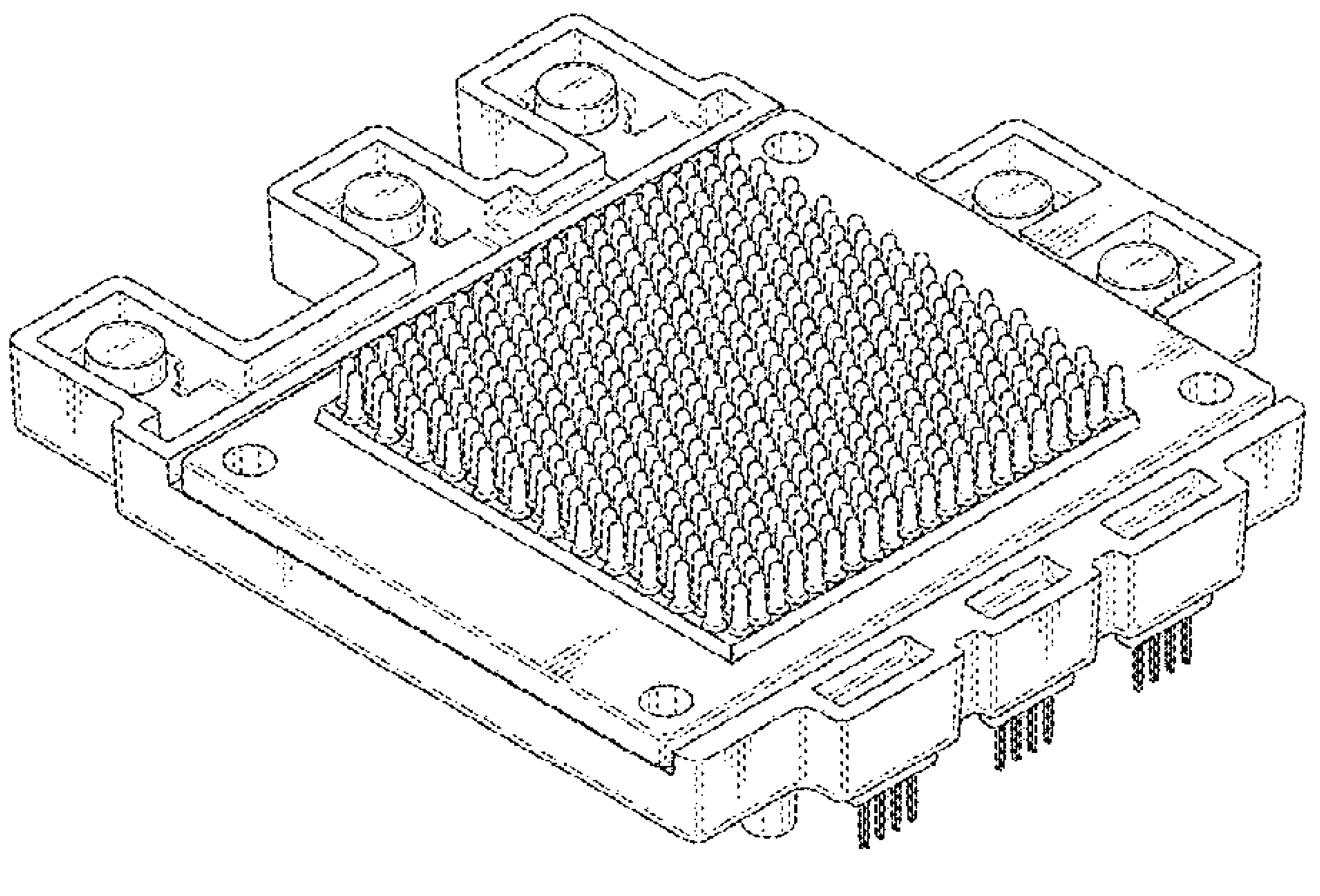
The ornamental design for a semiconductor device, as shown and described.

DESCRIPTION

FIG. **1** is a top, left and rear side perspective view of a semiconductor device, showing my new design;
FIG. **2** is bottom, right and rear side perspective view thereof;
FIG. **3** is a front elevational view thereof;
FIG. **4** is a rear elevational view thereof;
FIG. **5** is a left side elevational view thereof;
FIG. **6** is a right side elevational view thereof;
FIG. **7** is a top plan view thereof;
FIG. **8** is a bottom plan view thereof;
FIG. **9** is another top, left and rear side perspective view thereof, shown in a used condition mounted on a board shown in broken lines; and,
FIG. **10** is another rear view thereof, shown in a used condition mounted on a board shown in broken lines.
The broken lines shown in the drawing views in FIGS. **9** and **10** form no part of the claimed design.

1 Claim, 8 Drawing Sheets





Related U.S. Application Data

division of application No. 29/472,087, filed on Nov. 8, 2013, now Pat. No. Des. 754,084.

(58) **Field of Classification Search**

CPC 2924/1811; H01L 2924/1815; H01L 2924/19042; H01L 2224/08054; H01L 23/58; H05B 41/14; H05K 1/142; H05K 1/144; H05K 1/18; H05K 1/181; H05K 1/182; H05K 1/026

See application file for complete search history.

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Fig. 1

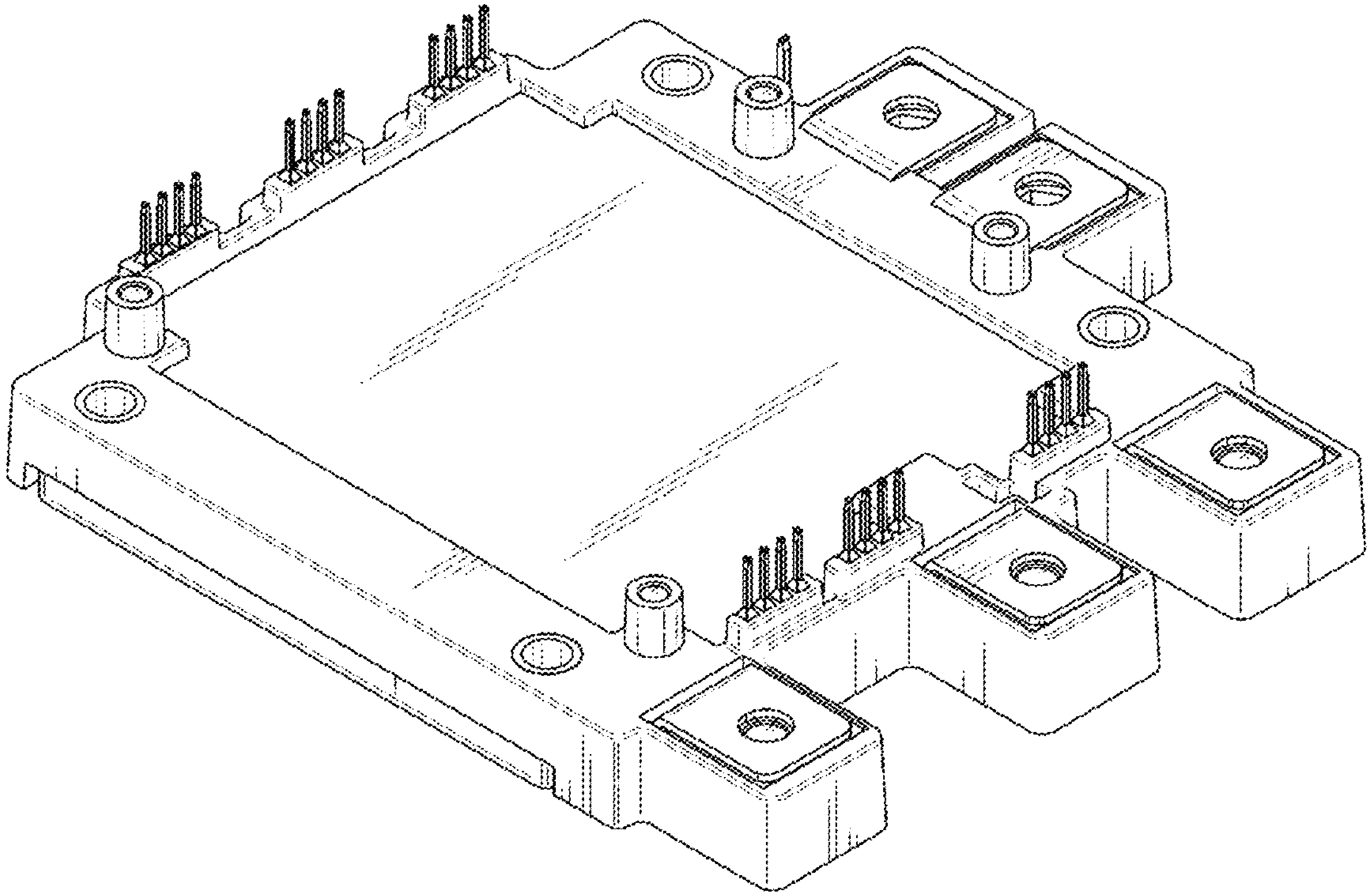


Fig. 2

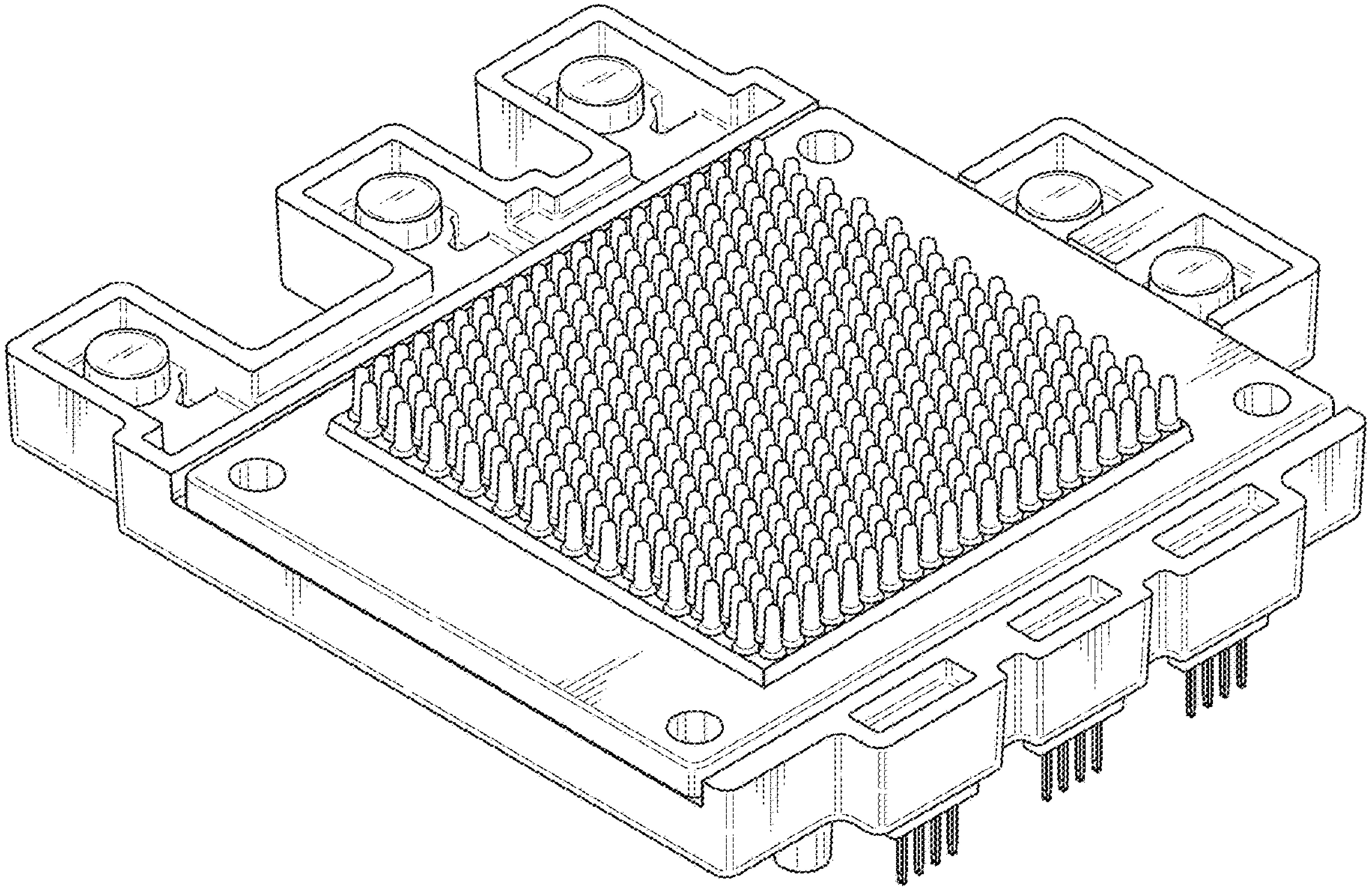


Fig. 3

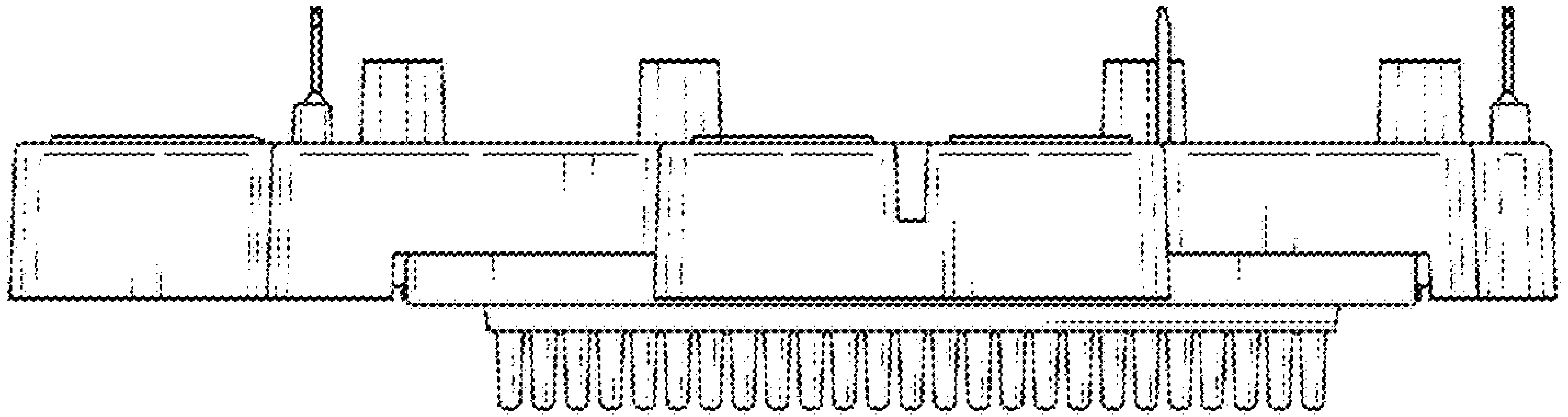


Fig. 4

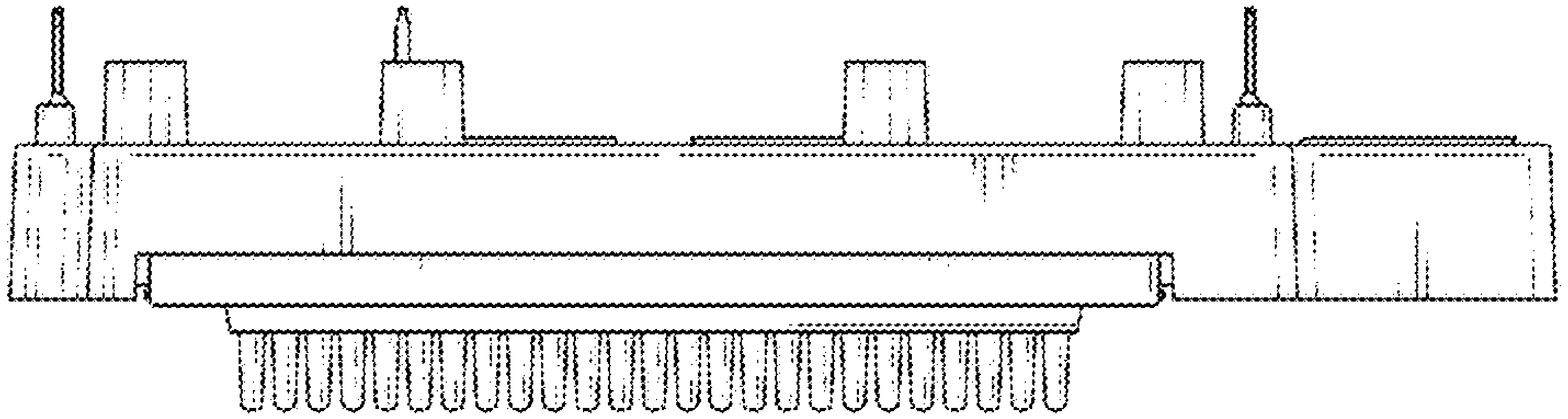
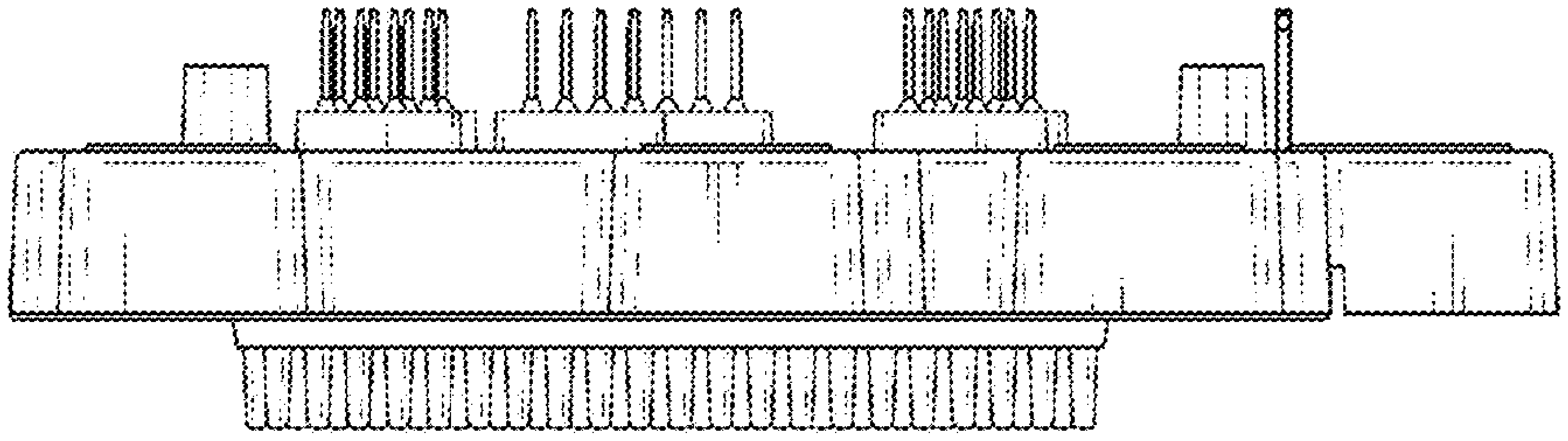


Fig. 5



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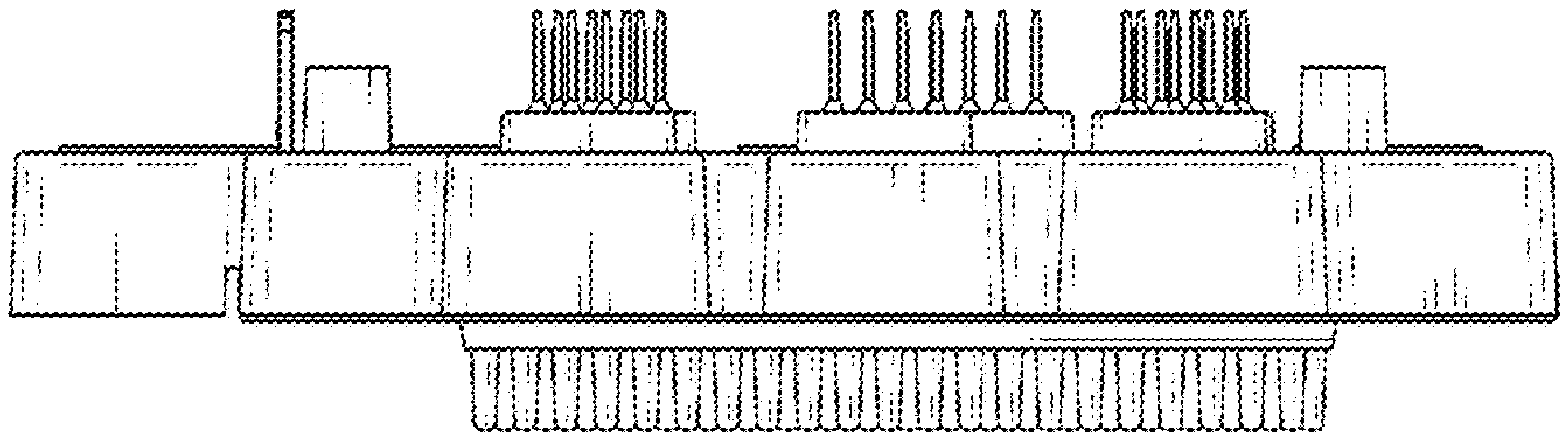
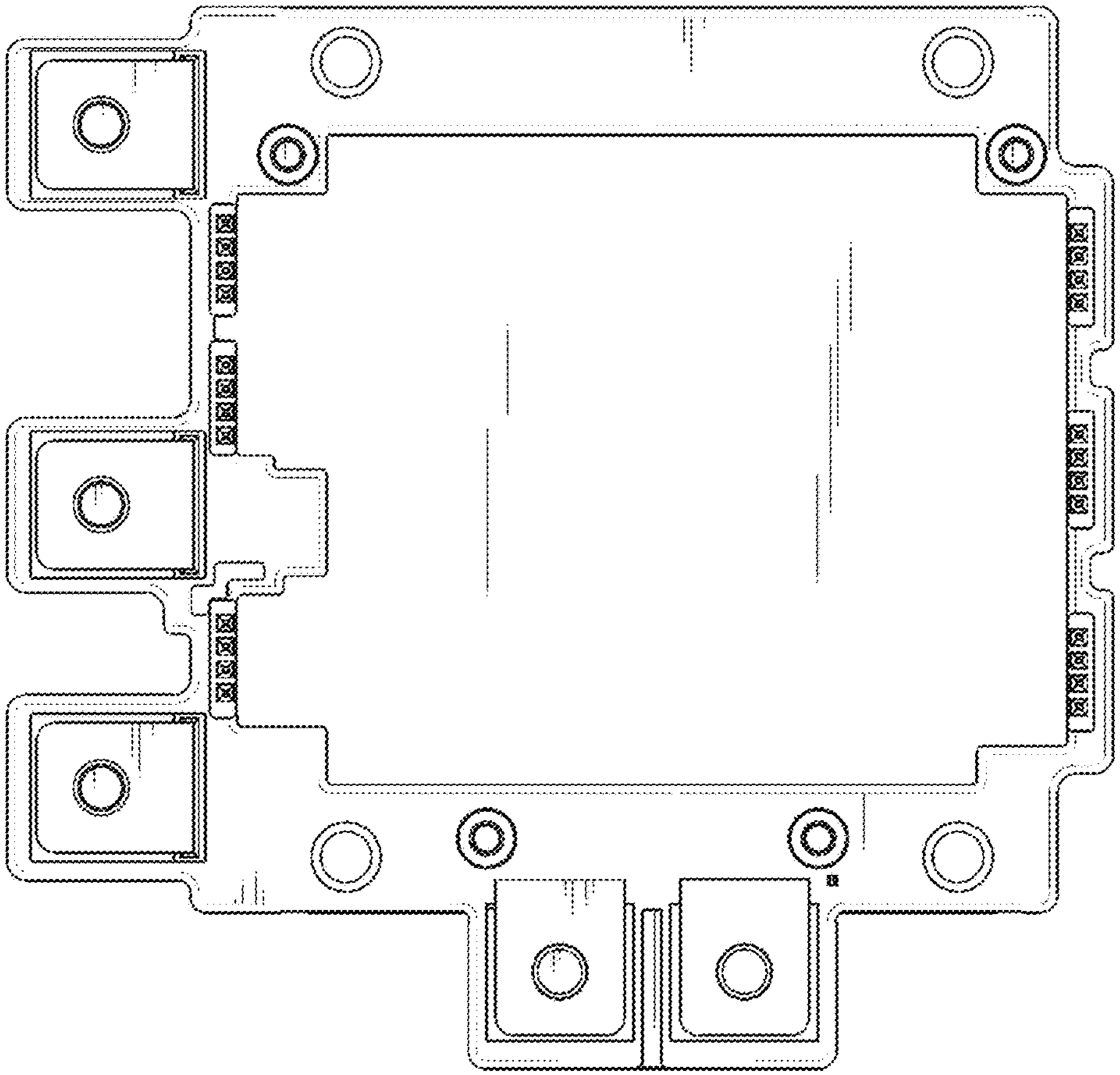


Fig. 7



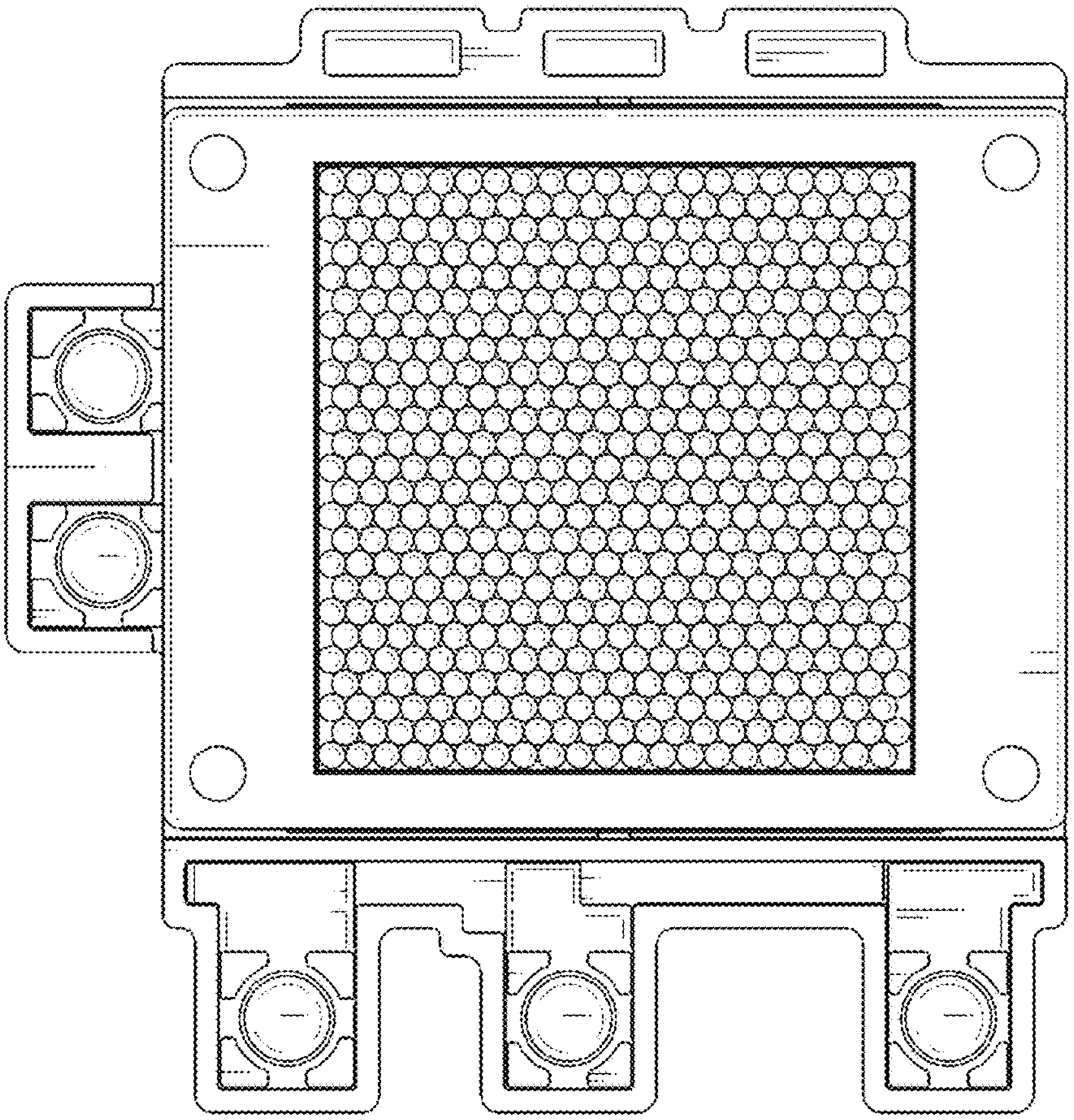


Fig. 8

Fig. 9

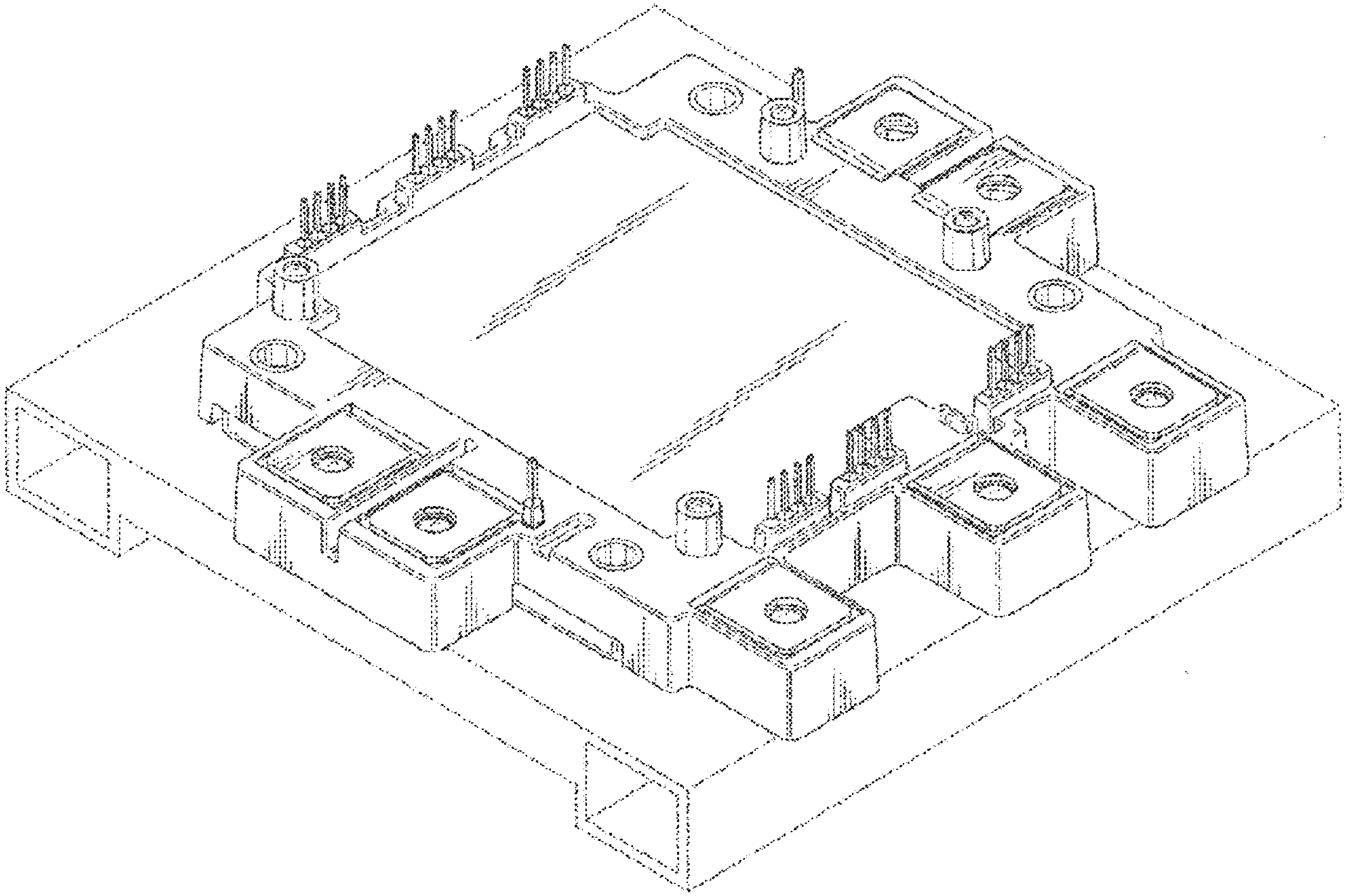


Fig. 10